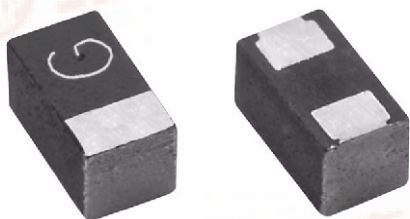


Solid Tantalum Chip Capacitors

MICROTAN™ High Reliability, Low DCL, Leadframeless Molded



FEATURES

- High reliability solid surface mount tantalum capacitors
- Low DCL for extended battery life
- Small sizes for space constrained applications
- L-shaped terminations for superior board mounting
- Suitable for medical implantable applications with additional screening
- Compliant to RoHS directive 2002/95/EC


RoHS
COMPLIANT

PERFORMANCE CHARACTERISTICS

Operating Temperature: - 55 °C to + 85 °C
(to + 125 °C with voltage derating)

Capacitance Range: 1 μF to 47 μF

Capacitance Tolerance: ± 10 % and ± 20 % standard

Voltage Range: 2 WV_{DC} to 40 WV_{DC}

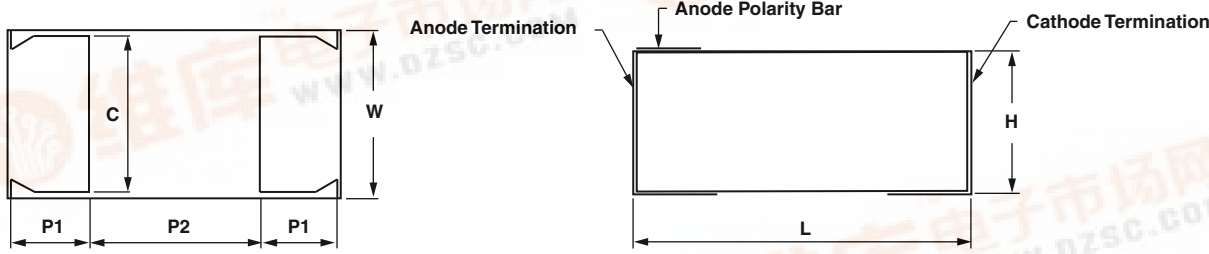
ORDERING INFORMATION

TM8 MODEL	R CASE CODE	106 CAPACITANCE	M CAPACITANCE TOLERANCE	016 DC VOLTAGE RATING AT + 85 °C	E TERMINATION/ PACKAGING	B RELIABILITY LEVEL	A SURGE CURRENT
	See Ratings and Case Codes Table	This is expressed in picofarads. The first two digits are the significant figures. The third is the number of zeros to follow.	K = ± 10 % M = ± 20 %	This is expressed in volts. To complete the three-digit block, zeros precede the voltage rating. A decimal point is indicated by an "R" (6R3 = 6.3 V).	E = Sn/Pb solder/ 7" (178 mm) reels R = Sn/Pb solder/ 7" (178 mm) 300 pcs. qty. C = 100 % tin/ 7" (178 mm) reels U = 100 % tin/ 7" (178 mm) 300 pcs. qty.	B = 0.1 % weibull FRL S = Hi-Rel std. (40 h burn-in) Z = Non-established reliability	A = 10 cycles at 25 °C B = 10 cycles at - 55 °C/+ 85 °C Z = None

Note

- Standard options are in bold

DIMENSIONS in inches [millimeters]

						
CASE	L	W	H	P1	P2 (REF.)	C
Q	0.100 ± 0.015 [2.54 ± 0.38]	0.053 ± 0.012 [1.35 ± 0.30]	0.050 ± 0.012 [1.27 ± 0.30]	0.031 + 0.004/- 0.006 [0.80 + 0.1/- 0.15]	0.038 ± 0.010 [0.96 ± 0.25]	0.046 + 0.009/- 0.001 [1.17 + 0.23/- 0.025]
D	0.150 ± 0.015 [3.8 ± 0.38]	0.100 ± 0.015 [2.54 ± 0.38]	0.050 ± 0.012 [1.27 ± 0.30]	0.031 + 0.004/- 0.006 [0.80 + 0.1/- 0.15]	0.088 ± 0.010 [2.24 ± 0.25]	0.091 + 0.009/- 0.001 [2.3 + 0.23/- 0.025]
E	0.201 ± 0.015 [5.1 ± 0.38]	0.100 ± 0.015 [2.54 ± 0.38]	0.050 ± 0.012 [1.27 ± 0.30]	0.031 + 0.004/- 0.006 [0.80 + 0.1/- 0.15]	0.139 ± 0.010 [3.5 ± 0.25]	0.091 + 0.009/- 0.001 [2.3 + 0.23/- 0.025]
F	0.220 ± 0.015 [5.6 ± 0.38]	0.138 ± 0.012 [3.5 ± 0.3]	0.050 ± 0.012 [1.27 ± 0.30]	0.039 ± 0.005 [1.0 ± 0.13]	0.142 ± 0.010 [3.6 ± 0.25]	0.126 + 0.009/- 0.001 [3.2 + 0.23/- 0.025]
K	0.045 ± 0.002 [1.14 ± 0.05]	0.026 ± 0.002 [0.66 ± 0.05]	0.024 max. [0.61 max.]	0.010 ± 0.004 [0.25 ± 0.1]	0.020 min. [0.51 min.]	0.015 ± 0.004 [0.38 ± 0.1]

Solid Tantalum Chip Capacitors
 MICROTAN™ High Reliability, Low DCL,
 Leadframeless Molded

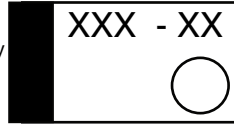
Vishay Sprague

DIMENSIONS in inches [millimeters]						
CASE	L	W	H	P1	P2 (REF.)	C
L	0.081 ± 0.008 [2.05 ± 0.2]	0.051 ± 0.004 [1.3 ± 0.10]	0.04 max. [1.0 max.]	0.020 ± 0.004 [0.50 ± 0.1]	0.027 min. [0.70 min.]	0.035 + 0.009/- 0.01 [0.9+0.23/- 0.02]
M	0.063 ± 0.006 [1.60 ± 0.15]	0.033 ± 0.006 [0.84 ± 0.15]	0.033 ± 0.006 [0.84 ± 0.15]	0.020 ± 0.004 [0.51 ± 0.1]	0.019 min. [0.48 min.]	0.024 ± 0.004 [0.61 ± 0.1]
N	0.138 + 0.004/- 0.008 [3.505 + 0.101/- 0.203]	0.110 ± 0.004 [2.80 ± 0.1]	0.04 max. [1.0 max.]	0.031 + 0.004/- 0.006 [0.80 + 0.1/- 0.15]	0.088 ± 0.010 [2.24 ± 0.25]	0.091 + 0.009/- 0.001 [2.3 + 0.23/- 0.025]
P	0.096 ± 0.006 [2.45 ± 0.15]	0.059 ± 0.006 [1.5 ± 0.15]	0.049 max. [1.25 max.]	0.020 ± 0.004 [0.51 ± 0.1]	0.043 min. [1.1 min.]	0.035 ± 0.004 [0.90 ± 0.1]
R	0.081 ± 0.006 [2.06 ± 0.15]	0.053 ± 0.006 [1.35 ± 0.15]	0.058 ± 0.004 [1.47 ± 0.10]	0.020 ± 0.004 [0.51 ± 0.1]	0.028 min. [0.71 min.]	0.035 ± 0.004 [0.90 ± 0.1]
T	0.138 + 0.004/- 0.008 [3.505 + 0.101/- 0.203]	0.110 ± 0.004 [2.80 ± 0.1]	0.06 max. [1.52 max.]	0.031 + 0.004/- 0.006 [0.80 + 0.1/- 0.15]	0.088 ± 0.010 [2.24 ± 0.25]	0.091 + 0.009/- 0.001 [2.3 + 0.23/- 0.025]
W	0.081 ± 0.006 [2.06 ± 0.15]	0.053 ± 0.006 [1.35 ± 0.15]	0.047 max. [1.2 max.]	0.020 ± 0.004 [0.51 ± 0.1]	0.028 min. [0.71 min.]	0.035 ± 0.004 [0.90 ± 0.1]

RATINGS AND CASE CODES						
F	6.3 V	10 V	16 V	20 V	25 V	40 V
1.0		M	M	W	R	P
2.2						
3.3				R		
4.7		M			P	
7.5		L		N*		
10	M	R	R			
15	M					
22						
33						
47		T				

Note

* Preliminary values, contact factory for availability.

MARKING	
M-Case Polarity Bar Voltage Code  K-Case 	P-Case Polarity Bar Voltage Code Capacitance Code  D, E, F, N, T-Case Capacitance Voltage  Polarity band Vishay logo (if space allows)

Solid Tantalum Chip Capacitors
MICROTAN™ High Reliability, Low DCL,
Leadframeless Molded

STANDARD RATINGS					
CAPACITANCE (μ F)	CASE CODE	PART NUMBER	MAX. DC LEAKAGE AT + 25 °C (μ A)	MAX. DF AT + 25 °C (%)	MAX. ESR AT + 25 °C 100 kHz STD. (Ω)
6.3 WV_{DC} AT + 85 °C, 4 WV_{DC} AT + 125 °C					
10	M	TM8M106(1)6R3(2)(3)(5)	0.32	8	5.0
15	M	TM8M156(1)6R3(2)(3)(5)	0.47	8	5.0
10 WV_{DC} AT + 85 °C, 7 WV_{DC} AT + 125 °C					
1.0	M	TM8M105(1)010(2)(3)(5)	0.20	6	12.0
4.7	M	TM8M475(1)010(2)(3)(5)	0.24	8	6.0
7.5	L	TM8L755(1)010(2)(3)(5)	0.38	8	8.0
10	R	TM8R106(1)010(2)(3)(5)	0.50	8	6.0
47	T	TM8T476(1)010(2)(3)(5)	2.35	8	1.0
16 WV_{DC} AT + 85 °C, 10 WV_{DC} AT + 125 °C					
1.0	M	TM8M105(1)016(2)(3)(5)	0.20	6	12.0
10	R	TM8R106(1)016(2)(3)(5)	0.80	8	6.0
20 WV_{DC} AT + 85 °C, 13 WV_{DC} AT + 125 °C					
1.0	W	TM8W105(1)020(2)(3)(5)	0.20	8	8.0
3.3	R	TM8R335(1)020(2)(3)(5)	0.33	8	8.0
7.5	N	TM8N755(1)020(2)(3)(5)*	0.93	8	8.0
25 WV_{DC} AT + 85 °C, 17 WV_{DC} AT + 125 °C					
1.0	R	TM8R105(1)025(2)(3)(5)	0.20	6	10.0
4.7	P	TM8P475(1)025(2)(3)(5)	0.59	6	6.0
40 WV_{DC} AT + 85 °C, 27 WV_{DC} AT + 125 °C					
1.0	P	TM8P105(1)040(2)(3)(5)	0.20	8	10.0

Notes

- (1) Capacitance tolerance: K, M
 (2) Termination and Packaging: E, C
 (3) Reliability level: Z, S, B
 (4) Reliability level: Z only
 (5) Surge current: Z, A, B
 (6) Surge current: Z only

* Preliminary ratings: contact factory for availability

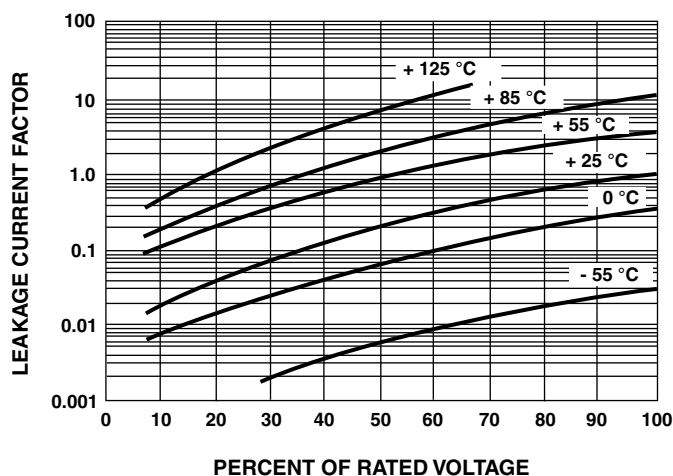
Solid Tantalum Chip Capacitors
MICROTAN™ High Reliability, Low DCL,
Leadframeless Molded

Vishay Sprague

CAPACITORS PERFORMANCE CHARACTERISTICS

ELECTRICAL PERFORMANCE CHARACTERISTICS		
ITEM	PERFORMANCE CHARACTERISTICS	
Category Temperature Range	- 55 °C to + 85 °C (to + 125 °C with voltage derating)	
Capacitance Tolerance	± 20 %, ± 10 % (at 120 Hz) 1 V _{rms} at + 25 °C using a capacitance bridge	
Dissipation Factor (at 120 Hz)	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 120 Hz.	
ESR (100 kHz)	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 100 kHz.	
Leakage Current	After application of rated voltage applied to capacitors for 5 minutes using a steady source of power with 1 kΩ resistor in series with the capacitor under test, leakage current at 25 °C is not more than described in Standard Ratings Table. Note that the leakage current varies with temperature and applied voltage. See graph below for the appropriate adjustment factor.	
Reverse Voltage	Capacitors are capable of withstanding peak voltages in the reverse direction equal to: 10 % of the DC rating at + 25 °C or 5 % of the DC rating at + 85 °C. Vishay does not recommended intentional or repetitive application of reverse voltage.	
Temperature Derating	If capacitors are to be used at temperatures above + 25 °C, the permissible rms ripple current or voltage shall be calculated using the derating factors: 1.0 at + 25 °C 0.9 at + 85 °C 0.4 at + 125 °C	
Operating Temperature	+ 85 °C RATING WORKING VOLTAGE (V) + 125 °C RATING WORKING VOLTAGE (V)	
	2	1.3
	4	2.7
	6.3	4
	10	7
	15	10
	16	10
	20	13
	25	17
	40	27

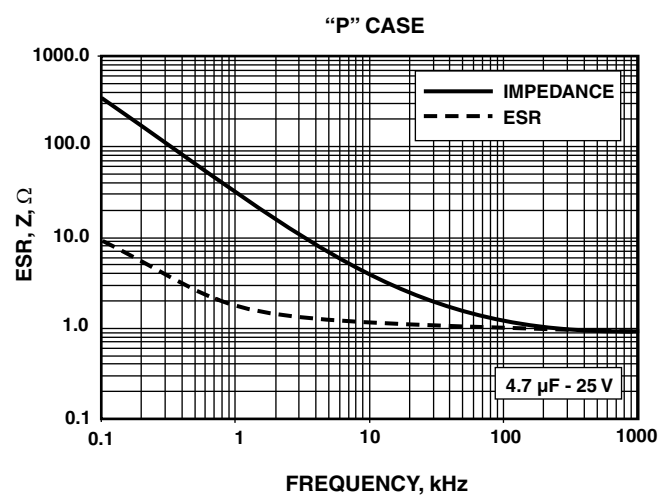
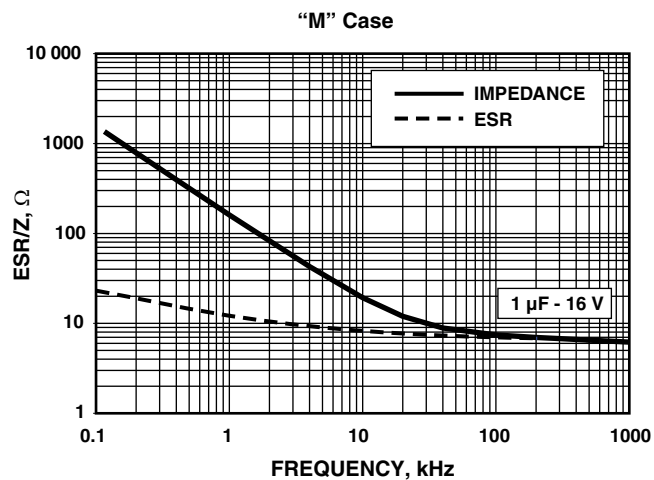
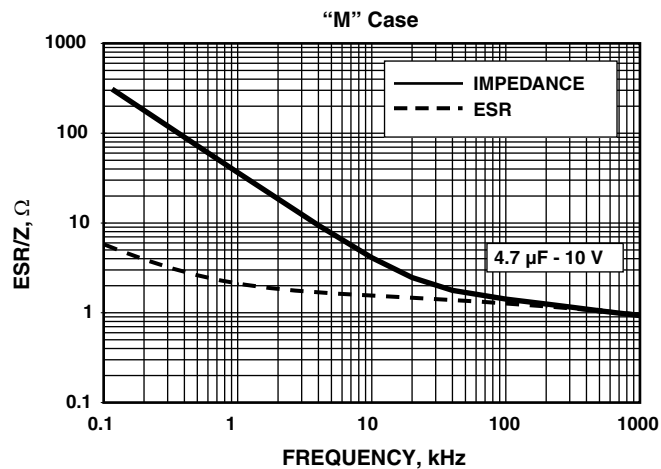
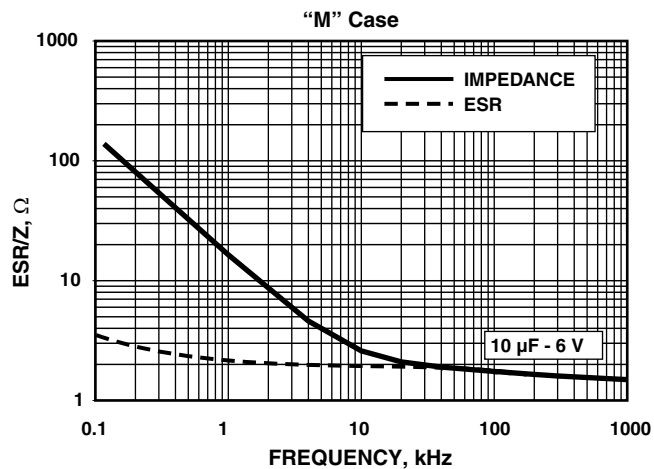
TYPICAL LEAKAGE CURRENT FACTOR RANGE



Notes

- At + 25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table
- At + 85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table
- At + 125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table

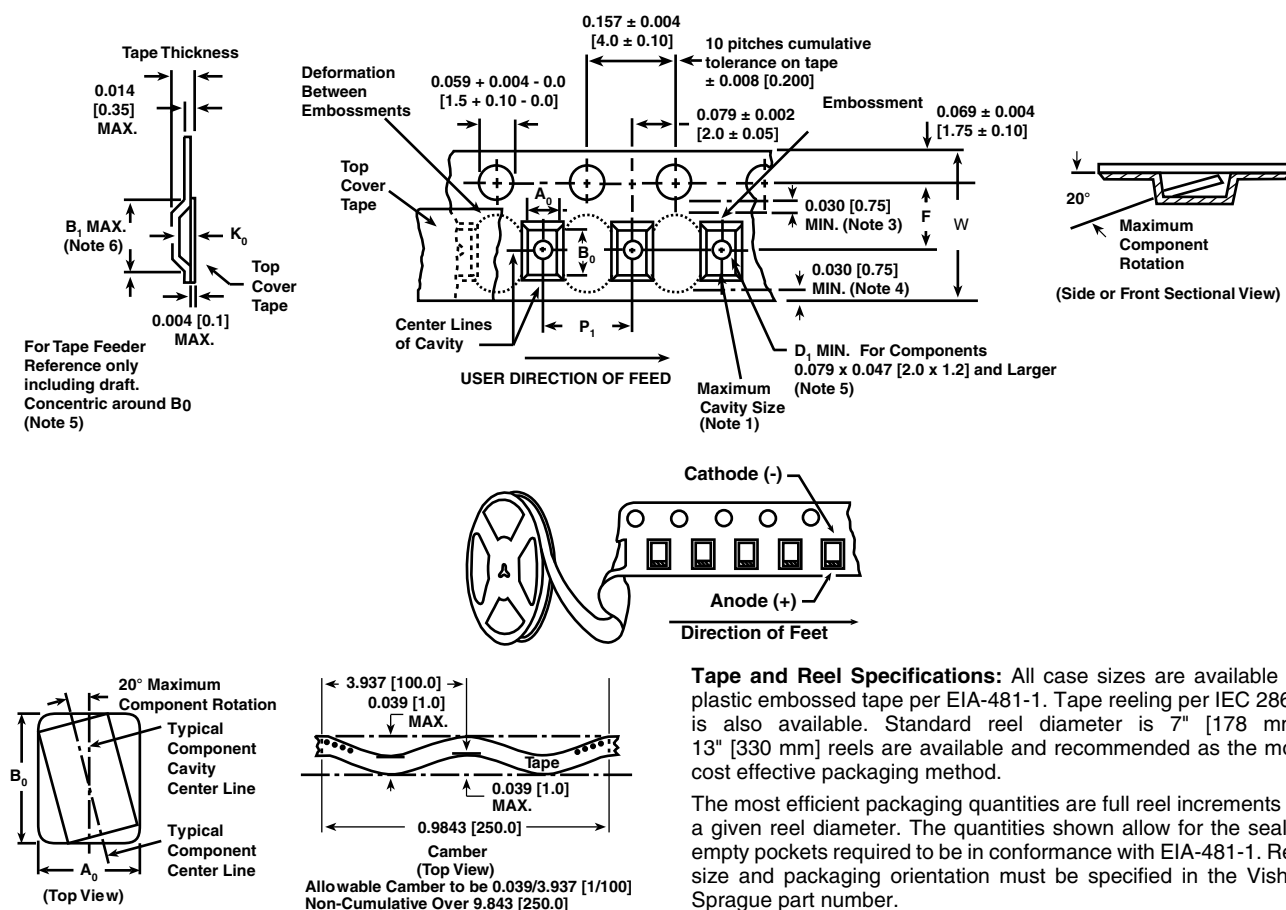
TYPICAL CURVES AT + 25 °C, IMPEDANCE AND ESR VS. FREQUENCY



Solid Tantalum Chip Capacitors
 MICROTAN™ High Reliability, Low DCL,
 Leadframeless Molded

Vishay Sprague

PLASTIC TAPE AND REEL PACKAGING in inches [millimeters]



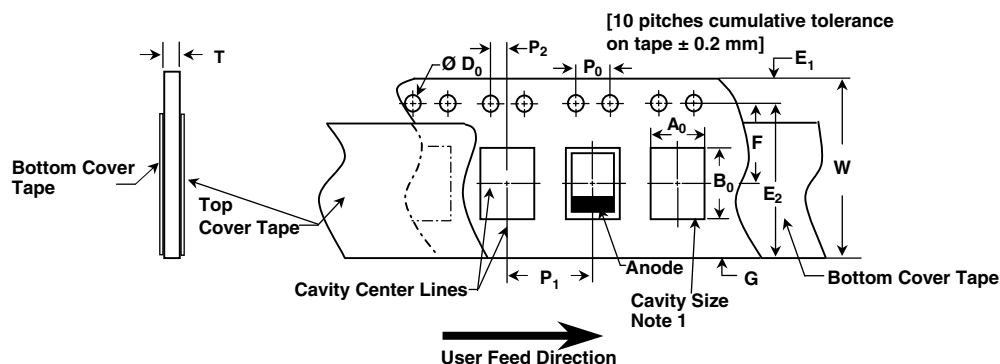
Note

Metric dimensions will govern. Dimensions in inches are rounded and for reference only.

CASE CODE	TAPE SIZE	B ₁ (MAX.)	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	W
TM8							
P	8 mm	0.108 (2.75)	0.039 (1.0)	0.138 (3.5)	0.054 (1.37)	0.157 (4.0)	0.315 (8.0)
Q	8 mm	0.135 (3.43)	0.039 (1.0)	0.138 (3.5)	0.065 (1.65)	0.157 (4.0)	0.315 (8.0)
L	8 mm	0.094 (2.4)	0.039 (1.0)	0.138 (3.5)	0.047 (1.2)	0.157 (4.0)	0.315 (8.0)
R	8 mm	0.112 (2.85)	0.039 (1.0)	0.138 (3.5)	0.066 (1.68)	0.157 (4.0)	0.315 (8.0)
W	8 mm	0.112 (2.85)	0.039 (1.0)	0.138 (3.5)	0.053 (1.35)	0.157 (4.0)	0.315 (8.0)
D	12 mm	0.154 (3.9)	0.059 (1.5)	0.216 (5.5)	0.051 (1.3)	0.157 (4.0)	0.472 (12.0)
E	12 mm	0.235 (5.97)	0.059 (1.5)	0.216 (5.5)	0.070 (1.78)	0.157 (4.0)	0.472 (12.0)
F	12 mm	0.231 (5.88)	0.059 (1.5)	0.216 (5.5)	0.060 (1.53)	0.157 (4.0)	0.472 (12.0)
N	12 mm	0.150 (3.8)	0.059 (1.5)	0.216 (5.5)	0.047 (1.2)	0.157 (4.0)	0.472 (12.0)
T	12 mm	0.150 (3.8)	0.059 (1.5)	0.216 (5.5)	0.063 (1.60)	0.157 (4.0)	0.472 (12.0)

Solid Tantalum Chip Capacitors
MICROTAN™ High Reliability, Low DCL,
Leadframeless Molded

PAPER TAPE AND REEL PACKAGING in inches [millimeters]



TM8

CASE SIZE	TAPE SIZE	A ₀	B ₀	D ₀	P ₀	P ₁	P ₂	E	F	W	T
K	8 mm	0.033 ± 0.002 [0.85 ± 0.05]	0.053 ± 0.002 [1.35 ± 0.05]	0.06 ± 0.004 [1.5 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.078 ± 0.004 [2.0 ± 0.1]	0.079 ± 0.002 [2.0 ± 0.05]	0.069 ± 0.004 [1.75 ± 0.1]	0.0138 ± 0.002 [3.5 ± 0.05]	0.315 ± 0.008 [8.0 ± 0.2]	0.03 ± 0.002 [0.75 ± 0.05]
M	8 mm	0.041 ± 0.002 [1.05 ± 0.05]	0.071 ± 0.002 [1.8 ± 0.05]	0.06 ± 0.004 [1.5 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.157 ± 0.004 [4.0 ± 0.1]	0.079 ± 0.002 [2.0 ± 0.05]	0.069 ± 0.004 [1.75 ± 0.1]	0.0138 ± 0.002 [3.5 ± 0.05]	0.315 ± 0.008 [8.0 ± 0.2]	0.037 ± 0.002 [0.95 ± 0.05]

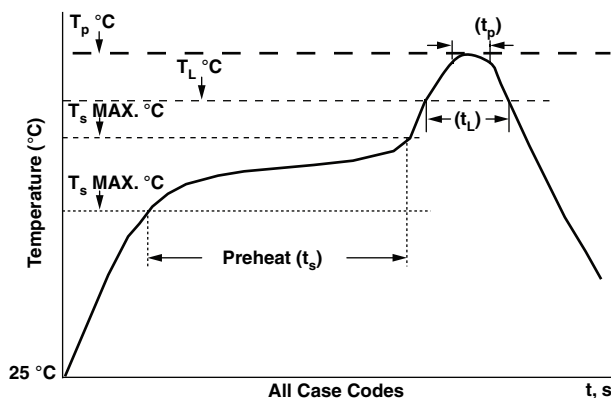
STANDARD PACKAGING QUANTITY

SERIES	CASE CODE	QTY (PCS/REEL)		
		7" REEL	1/2 REEL	SMALL REEL
TM8	K	5000	2500	300
	M	4000	2000	300
	P	3000	1500	300
	Q	4000	2000	300
	D	2500	1250	300
	E	2500	1250	300
	F	2500	1250	300
	L	2500	1250	300
	N	2500	1250	300
	R	2500	1250	300
	T	2500	1250	300
	W	2500	1250	300

POWER DISSIPATION

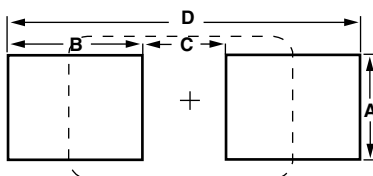
SERIES	CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT + 25 °C (W) IN FREE AIR
TM8	K	0.015
	M	0.025
	P	0.045
	Q	0.045
	D	0.084
	E	0.090
	F	0.110
	L	0.035
	N	0.075
	R	0.045
	T	0.084
	W	0.040

RECOMMENDED REFLOW PROFILES



TYPE	T_p lead (Pb)-free	T_p Sn/Pb	t_p	T_L lead (Pb)-free	T_L Sn/Pb	T_s MIN. lead (Pb)-free	T_s MIN. Sn/Pb	T_s MAX. lead (Pb)-free	T_s MAX. Sn/Pb	t_s lead (Pb)-free	t_s Sn/Pb	t_L
TM8	260 °C	225 °C	10	217 °C	183 °C	150 °C	100 °C	200 °C	150 °C	60 to 150	60 to 90	60

PAD DIMENSIONS in inches [millimeters]



CASE CODE	A (MIN.)	B (NOM.)	C (NOM.)	D (NOM.)
TM8				
K	0.028 (0.70)	0.018 (0.45)	0.024 (0.60)	0.059 (1.50)
M	0.039 (1.00)	0.028 (0.70)	0.24 (0.60)	0.080 (2.00)
P	0.063 (1.60)	0.031 (0.80)	0.047 (1.20)	0.110 (2.80)
Q	0.065 (1.60)	0.050 (1.30)	0.040 (1.00)	0.142 (3.60)
D	0.115 (2.90)	0.070 (1.80)	0.070 (1.80)	0.213 (5.40)
E	0.115 (2.90)	0.070 (1.80)	0.120 (3.00)	0.260 (6.60)
F	0.150 (3.80)	0.070 (1.80)	0.140 (3.60)	0.283 (7.20)
L	0.059 (1.50)	0.031 (0.80)	0.039 (1.00)	0.102 (2.60)
N	0.118 (3.00)	0.067 (1.70)	0.051 (1.30)	0.185 (4.70)
R	0.059 (1.50)	0.031 (0.80)	0.039 (1.00)	0.102 (2.60)
T	0.118 (3.00)	0.067 (1.70)	0.051 (1.30)	0.185 (4.70)
W	0.059 (1.50)	0.031 (0.80)	0.039 (1.00)	0.102 (2.60)

Solid Tantalum Chip Capacitors

MICROTAN™ High Reliability, Low DCL, Leadframeless Molded

GUIDE TO APPLICATION

1. **A-C Ripple Current:** The maximum allowable ripple current shall be determined from the formula:

$$I_{rms} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = Power dissipation in watts at + 25 °C as given in the table in paragraph number 5 (power dissipation).

R_{ESR} = The capacitor equivalent series resistance at the specified frequency.

2. **A-C Ripple Voltage:** The maximum allowable ripple voltage shall be determined from the formula:

$$V_{rms} = Z \sqrt{\frac{P}{R_{ESR}}}$$

or, from the formula:

$$V_{rms} = I_{rms} \times Z$$

where,

P = Power dissipation in watts at + 25 °C as given in the table in paragraph number 5 (power dissipation).

R_{ESR} = The capacitor equivalent series resistance at the specified frequency.

Z = The capacitor impedance at the specified frequency.

- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at + 25 °C.
3. **Reverse Voltage:** These capacitors are capable of withstanding peak voltages in the reverse direction equal to 10 % of the DC rating at + 25 °C, 5 % of the DC rating at + 85 °C and 1 % of the DC rating at + 125 °C.
4. **Temperature Derating:** If these capacitors are to be operated at temperatures above + 25 °C, the permissible rms ripple current or voltage shall be calculated using the derating factors as shown:

TEMPERATURE	DERATING FACTOR
+ 25 °C	1.0
+ 85 °C	0.9
+ 125 °C	0.4

5. **Power Dissipation:** Power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_{rms} value be established when calculating permissible operating levels. (Power Dissipation calculated using + 25 °C temperature rise.)

6. **Printed Circuit Board Materials:** Molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelainized steel).

7. **Attachment:**

- 7.1 **Solder Paste:** The recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.

- 7.2 **Soldering:** Capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering and hot plate methods. The Soldering Profile charts show recommended time/temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 2 °C per second. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor.

- 7.2.1 **Backward and Forward Compatibility:** Capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.

8. **Cleaning (Flux Removal) After Soldering:** Molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chloroethane, Terpene and aqueous cleaning media. However, CFC/ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.

- 8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. DO NOT EXCEED 9W/l at 40 kHz for 2 minutes.

9. **Recommended Mounting Pad Geometries:** Proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and/or circuit board design.

Disclaimer

All product specifications and data are subject to change without notice.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained herein or in any other disclosure relating to any product.

Vishay disclaims any and all liability arising out of the use or application of any product described herein or of any information provided herein to the maximum extent permitted by law. The product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein, which apply to these products.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications unless otherwise expressly indicated. Customers using or selling Vishay products not expressly indicated for use in such applications do so entirely at their own risk and agree to fully indemnify Vishay for any damages arising or resulting from such use or sale. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

Product names and markings noted herein may be trademarks of their respective owners.